

## World's Largest Congress for Automotive Electronics, Software and Applications

October 16-17, 2024, Bonn, Germany

Hand in your abstract  
**by March 1, 2024**

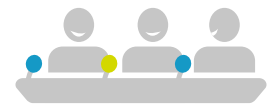
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# Call for Papers

ANNUALLY  
from 2024

### Key Topics 2024:

- Cross-Sectional Topics
- Software
- Automotive AI
- Automated Driving
- Cockpit & Customer Experience
- Mobility System Architecture
- Cloud Technologies and Data
- Security
- E-Vehicle/Mobility
- Processes: Virtual, Simulation & Validation
- Electronics Technology/Hardware
- Connectivity/OTA



## The Need For Speed

In the last ELIV 2023, the decision to hold ELIV annually from this year onwards was reinforced. Many participants confirmed that it is extremely useful in their day-to-day work to be regularly informed about and discuss strategies as well as technical innovations. This also includes impulses from new players and the industries with which we are increasingly intertwined. Even partnerships have been formed at ELIV. Everything is gaining momentum. We are not only talking about the strategies and innovations of the all-determining CASE Megatrends (Connected, Autonomous, Shared, Electric) but also about how to get products to customers quickly. Speed is a decisive success factor – more than ever before. Bringing innovations to market quickly, shortening development times and validations, reacting quickly to new trends, and keeping up with international competition.

We noticed that the topic of speed came up in many discussions at ELIV 2023. So let's take a closer look at the key topics that need to be discussed in 2024:

Software-oriented technologies such as Artificial Intelligence, Cyber Security, Data Management, Ecosystems, Cloud and Open Source for electric, autonomous, and connected vehicles. The continuation of the Open Source discussion has been requested by many participants. Semiconductors are playing an increasingly important role in this. The deepening of the process world with the latest, often virtual, approaches to simulation, integration, and validation with the associated tools and standards will also have its place in the range of topics. 'Architecture for Vehicles' has not gone far enough; we have to talk about 'Mobility System Architecture' and the interface to the customer, e.g., in the cockpit. Key markets such as China with country-specific requirements will play a special role in the congress.

We are happy to expand the scope and offer you the opportunity to find fellow campaigners for your innovative ideas for implementing the software-defined vehicle. It would be desirable if you could be part of the largest networking event of its kind in the world and submit an abstract of your presentation. Subsequently, we will again conduct a joint evaluation with the top-class program committee members from OEMs, suppliers, and technology companies and put together an attractive program.

We hope to have aroused your enthusiasm and look forward to receiving your submissions at a time when the speed of the vehicle itself seems to be becoming less relevant than the speed of product development and data. Electronics have always been fast. Let's step it up a notch!

**Dr. Rolf Zöller**, Chairman of the Program Committee

**Uwe Michael**, Member of the Program Committee

## Program Committee



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**Dr. Rolf Zöller**, Director Smart Connected Vehicle Porsche AG and Managing Director Porsche Digital, Weissach (Chair)

# General Information

## Call for papers

Are you an expert in one of the fields listed under key topics? If so, we ask you to contribute actively to the success of this congress with a lecture.

Please submit an abstract not exceeding one A4 page **by March 1, 2024**. You can register with your contribution online at [www.eliv-congress.com](http://www.eliv-congress.com).

### The abstract must include (one A4 page maximum):

- The informative title of your contribution
- Details of the speaker and the co-authors (names and contact details)
- A summary with specific information
- A statement as to the degree of innovation
- The assignment to which key topic (in the Word file as well, please)
- Indication of publications on the topic

Upon submission of their abstract all submitters will receive a questionnaire asking them to give some specific details about their presentation.

In the interest of all participants, we ask you to refrain from straightforward product presentations. The focus of the congress should be on the exchange of information and ideas regarding the latest solutions, products, developments and technologies. The program committee will decide on the acceptance and classification of a paper in the congress program.

## Evaluation criteria for the abstracts

Following the submission deadline, the program committee will evaluate the submitted abstracts. To make the selection process and criteria more transparent, the latter are described below.

## Content

- Topicality: Does the subject currently and will it in future play a role in industry and/or science? Has this contribution already been presented at another event?
- Newness content (degree of innovation): Are new approaches/ideas proposed or is the product/method etc. already in use?
- Relevance of the topic: Is the topic relevant to the congress? Can the topic be found under the key topics?
- State of development: Will the product, service or the like dealt with in the lecture soon be ready for series production or is it already in series production?
- Holistic approach: Is there a holistic approach?
- Application-related: Can the innovation or solution presented in the lecture already be implemented? Are there any field reports? What benefit can listeners draw from the lecture?
- Scientific level: Are there any references?
- Does the lecture include a strategic statement, recommendation for action or standardisation proposals?

## Quality of the abstract

- Is there compliance with the formal conditions at submission of the abstract? (one DIN A4 page)
- Is a common theme recognizable?
- What scope does the topic offer? In-depth treatment?
- Is the content presented clearly and understandably?

## Profile of the lecturer

- How many years of experience in the automotive industry?
- References

## General information (abstracts and manuscripts)

- Please submit abstracts in English.
- The duration of lectures will be approximately 25 minutes followed

by a discussion of about 5 minutes. The authors of the accepted papers undertake to submit a detailed manuscript (no more than 10-12 pages).

- The manuscripts will be published in a VDI report in the download area of the homepage.
- The manuscript as well as the presentation slides are to be written in English.
- In addition to the manuscript, the speakers are asked, a few weeks before the congress, to indicate the 3 or 4 most important key statements of the lecture. Speakers will receive further information in this regard separately.

## Costs

- Speakers (one author per lecture) will participate in the congress free of charge. Travel and accommodation costs will not be refunded.

## Congress language

English

## Deadlines

Deadline for abstracts: **March 1, 2024**

Notification of authors: **End of April 2024**

Submission deadline for final manuscripts: **September 2, 2024**

Submission deadline for submission of 3 or 4 most important key statements: **September 2, 2024**

## Young talent award "Auto-Electronic Excellence Award 2024"

Once again in 2024 the three best young lecturers (up to and including 33 years) will be honored with the Auto-Electronics Excellence Award 2024. The experts of the program committee rate the lectures according to numerous criteria such as degree of novelty, scientific level and application relevance. At the end of the event the congress organizer will present the prizes to the winners. (Prizes can be accepted only in person. Acceptance at a later date or the appointment of a representative is not possible.)

## Technical sponsor: the VDI Society for Vehicle and Traffic Systems Technology

**VDI** With its eight technical divisions, the VDI Society for Vehicle and Traffic Systems Technology forms a home for engineers of various disciplines in the field associated with the transport modes of road, rail, air and water. In an active interaction with the working groups of the VDI district associations, students and young engineers as well as other VDI societies, the VDI Society for Vehicle and Traffic Systems Technology is networked with other cooperation partners both nationally and internationally.

For more information, please visit: [www.vdi.de/fvt](http://www.vdi.de/fvt)  
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## Your Contact Persons

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# Please submit on the following Key Topics 2024

## Cross-Sectional Topics

- Need for speed: Speed up development and processes
- Potential partner countries (China, Sweden, France)
- Laws, regulations and (virtual) homologation
- Standards
- Partnership management
- Carbon footprint
- Internationalization
- Business models
- Patents & licences
- Strategies
- Learning from other industries
- Cost aspects
- Weight
- Verification & validation
- Digital transformation
- Cultural aspects
- New way of working
- Automotive market
- Execution experiences
- Supplier-OEM-relationship in the „New World“
- Contribution of automotive development to the UN SDG

## Software



- Software technologies
- Open Source software & tools
- API-Technologies
- Software platforms
- Software architecture
- Software defined vehicle
- Open standards (Architecture, APIs, Middleware)
- Middleware and operating systems e.g. Android, Linux, Autosar
- Hypervisors suspend to RAM
- OTA, software update strategies
- Diagnostics
- Reuseability
- SIL/HIL/MIL
- APP Framework
- Licence management
- Development infrastructure
- Ecosystem
- Shared software platforms make - buy - shared (e.g. SOAFEE, Eclipse etc.)
- Edge computing
- DevOps
- Open Source initiatives
- CI/CD chains
- Scalability
- Managed APIs
- ASIL B compliance
- Managing complexity
- On-/Offboard functionality
- Potential trends within embedded systems
- Credible simulation, virtual testing
- MCU/SOC role for future software
- Data driven development
- RDS (Reliable Distributed System)
- Integration
- Sustainable software development
- Virtual Vehicle – digital twin
- Embedded visual odometry
- Collaborative topics
- Software Life-Cycle-Management
- ISA parity in cloud and vehicle
- Standardization of APIs
- System architecture modelling tools
- Concrete projects within Open Source consortia

## Electronics Technology/ Hardware



- System on chip (SOC)
- High performance computing hardware
- Microcontroller and high performance controller
- Mechanics/Mechatronics
- Electronics components
- Lighting experience
- Weight reduction
- EMC
- Vehicle access systems
- ECUs
- After sales and (self)diagnostics
- Networking technology (CAN FD, Lin, CAN XL, Ethernet etc.)
- Semiconductor
- Chiplets
- Emerging network standards
- Sensors and actuators
- High performance computing
- Hardware abstraction
- Zone controller
- Power management
- Edge hardware

## Automotive AI



- Automotive applications
- AI based testing and validation
- Remote diagnostics with advanced machine learning
- Embedded machine learning
- Predictive maintenance
- Data-driven development
- Data factory
- Digital assistant
- Connected services/cockpit
- Use cases with AI
- Avatar
- ChatGPT
- Neural networks
- Generative AI
- Image processing
- Next generation
- Usage of GenAI
- AI based software development
- AI in functional safety chains

## Automated Driving



- ADAS Level 2 to 5
- V2X solutions
- AI (Perception of environment and tracking)
- Software stack AD
- HD Map
- Sensors: Radar, Lidar etc.
- Cooperative perception, infrastructure and vehicle
- Object detection
- Actual projects on ADAS
- Position (hybrid collaborative positioning, live map)
- Safety (architecture and virtualization)
- Next generation sensor fusion
- Trajectory planning and motion control
- Functional safety, SOTIF and security
- Securing autonomous functions
- NCAP
- Simulation technologies HAF
- Smart infrastructure - international
- ADAS specific law & regulation
- Chinese solution
- Data collection
- Commercial vehicle experiences
- Validation/verification of AD functions
- Virtual homologation
- Semiconductors for ADAS/AD

## Cloud Technologies and Data



- Data analytics
- Distributed data management
- Data handling - Big data
- Service backend system
- Data compression
- Healthy vehicle, maintenance (cloud-based)
- Data backends regional characteristics
- Application of data analytics & management
- Ecosystems
- Vehicle backend, backend connection
- Connected services
- Cloud computing
- Edge device technology
- Digital twins
- Big data analyse
- Cloud/web services
- Shift to cloud
- Data acquisition
- Data-driven decisions

## Mobility System Architecture



- Domain-, zone-architectures
- Function based architecture
- On-/Offboard architecture
- From signal to service orientation
- Architecture development
- High performance computing hardware
- Complexity management
- Life-Cycle-Management
- Energy management
- Upgradeability
- Electrical harness and power distribution
- Diagnostics
- E/E architectures for ADAS
- Wiring harness
- Connectors
- Design for automatization
- Central architectures
- Service based communication
- Scalability
- Decoupling of domains
- Domain controllers
- Middleware
- Liquid cooling

## Processes: Virtual, Simulation & Validation



- PMT processes, methods and tools
- Testing methods (OTA)
- Virtual, model based testing
- Risk management
- Continuous-X
- Integration processes
- Change management
- (Model based) testing
- Requirements management
- Maturity management
- Automotive Spice, UNECE, ISO 26262
- DevOps
- Software configuration management
- Model based design
- Quality methods
- Agile in automotive
- Scrum master
- Innovation management
- Complexity management
- Version management
- Manufacturing process
- System engineering
- Model based design
- Vertical integration
- MVP
- Virtualized integration
- Digital Life-Cycle-Management
- Virtual platforms

## E-Vehicle/Mobility



- Power electronics, battery capacity
- Batterie in the cloud
- Mobility services
- Mobility prediction
- Battery/Energy management concepts (BMS)
- Range management
- Charging of e-vehicles
- Smart grid
- Infrastructure of e-vehicle charging
- Wireless and HPC charging
- Mega watt charging
- Battery simulation
- Cell technologies next generation
- Impact of raw materials: Lithium, Cobalt, Copper etc.
- Power electronics and DC/DC converters – SiC, GaN etc.
- Battery ageing and second life
- Battery technologies (Li)
- Design of HV batteries
- High voltage safety
- Batteries in mobility (cars, two wheelers etc.)
- E-drive integration
- Thermal management in e-vehicles
- Vehicle concepts with e-drive
- HV battery testing/transport/maintenance/recycling
- 800 Volt
- 48 Volt
- Hydrogen
- eFuses
- Energy management
- Vehicle to grid track

## Security



- Automotive security concepts
- OTA
- Intrusion detection
- DevSecOps
- Regulations
- Elements of security concepts
- Validation and monitoring of the security chain
- Standardization of cyber security systems
- Compliance and legal aspects
- Holistic concept for the ecosystem
- Cyber security
- Macsec, Secoc experiences
- Impact of quantum computing on vehicle security
- Global and local cyber security concepts
- ISO/SAE 21434 and others
- Test validation
- UN regulation 155, ISO/SAE 21434 NIS 2 regulation
- Early detection
- Experiences
- EVSE
- Components and solutions
- Requirements

## Connectivity/OTA



- Function on demand
- OTA
- 5/6 G technology and applications in vehicles
- Vehicle tracking
- Intelligent connected vehicle standard
- Connectivity, IoT, cloud
- Edge computing
- End2end functionality
- Projected mode
- Coverage
- V2X
- MQTT
- Service oriented communication
- Ethernet
- Terrestrial and satellite mobile communications

## Cockpit & Customer Experience



- Display and camera sensors
- Driver monitoring systems
- Digital assist
- Large language model
- Infotainment services
- Vision technologies
- Interior/Driver monitoring
- Navigation
- In cabin sensing
- In-car office
- New cluster instrument concepts
- Customer journey
- Innovative UX solutions
- China UX concepts
- Personalization
- Speech recognition technologies
- Context related UX
- Driver distraction and monitoring
- User interfaces/touch points
- Audio technologies/architectures
- Sound system
- Welcome szenarios
- Co-Pilot
- Studies on criteria of end users
- Infotainment/premium audio
- HUD, Augmented reality, 3D
- Connected experience UX
- Avatar
- Consumer integration – smart home, smart phone
- Intelligent interior illumination
- Gesture control
- Multimodal operation
- Connected services
- Gaming

# Exhibition & Sponsoring

The international congress ELIV is the world's largest congress for automotive electronics, software and applications. Once again, in 2024, at the trade show accompanying the congress, more than 100 companies will present innovative and forward-looking products and services from the industry. The exhibition is the central marketplace of the congress, where congress participants can catch up on trends in the industry. Take advantage of this attractive platform for corporate presentation and boost your advertising impact. Become an exhibitor or a sponsor and impress the leading decision-makers in the industry.

Don't hesitate to contact us for further information on the exhibition and sponsoring:



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and



**Martina Slominski,**  
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## Who should be exhibitor?

Manufacturers, suppliers and service providers of the automotive industry covering the following areas:

- Software and connected systems
- Automated driving and driver assistance systems
- Electrical power supply/E-mobility
- Electronic components and control devices
- Infotainment
- Comfort electronics
- HMI, operation and display
- Lighting and visibility
- Diagnostics/testing/integration
- Development services
- Start-ups
- etc.

## Sponsors 2023:

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**Please note:**  
If your registration as exhibitor or sponsor is received by May 6, 2024 your company name will be printed in the exhibitors' list as part of the program brochure. This flyer will be sent out to some 10,000 selected addresses in Germany and abroad!

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